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HIRAGA et al.(10) **Pub. No.: US 2018/0061900 A1**(43) **Pub. Date: Mar. 1, 2018**(54) **DISPLAY DEVICE**(71) Applicant: **Japan Display Inc., Tokyo (JP)**(72) Inventors: **Kenta HIRAGA, Tokyo (JP); Hajime Akimoto, Tokyo (JP)**(21) Appl. No.: **15/681,642**(22) Filed: **Aug. 21, 2017**(30) **Foreign Application Priority Data**

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(57)

ABSTRACT

A display device in an embodiment according to the present invention includes a substrate, a plurality of wirings above the insulation surface, an interlayer insulation layer covering the plurality of wirings, a light emitting element above the interlayer insulation layer, a first inorganic insulation layer covering the light emitting element, a first detection electrode extending in a first direction above the first inorganic insulation layer, an organic insulation layer above the first inorganic insulation layer covering the first detection electrode, a second detection electrode extending in a second direction intersecting the first direction above the organic insulation layer, a second inorganic insulation layer above the organic insulation layer covering the second detection electrode, a first connection wiring electrically connecting the first detection electrode and one of the plurality of wirings, and a second connection wiring electrically connecting the second detection electrode and another one of the plurality of wirings.

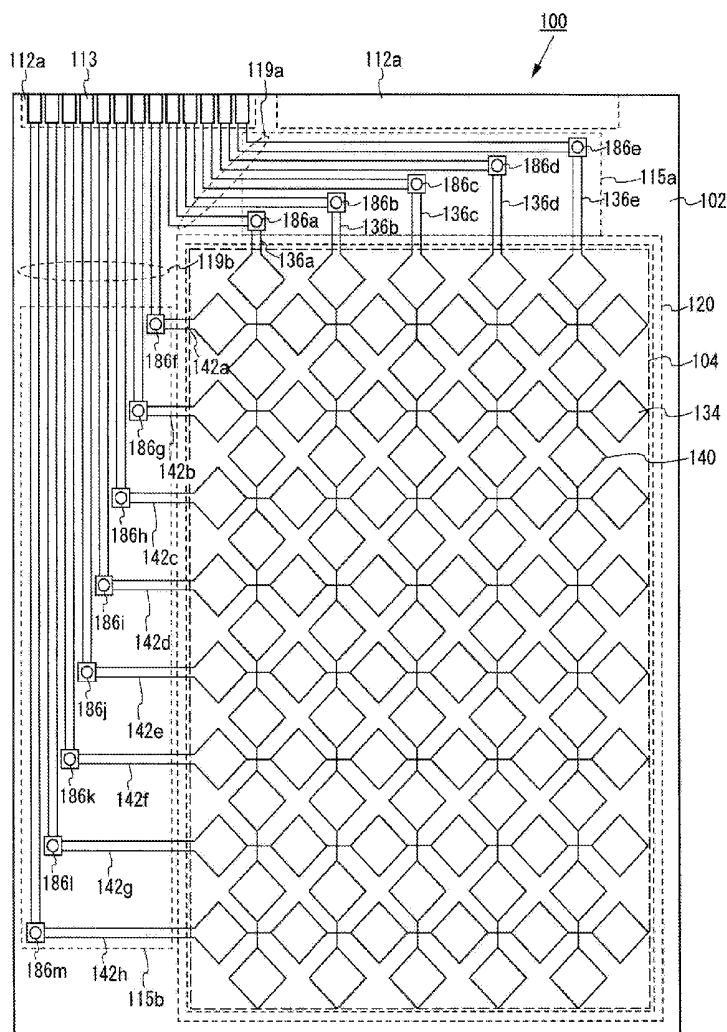


FIG. 1

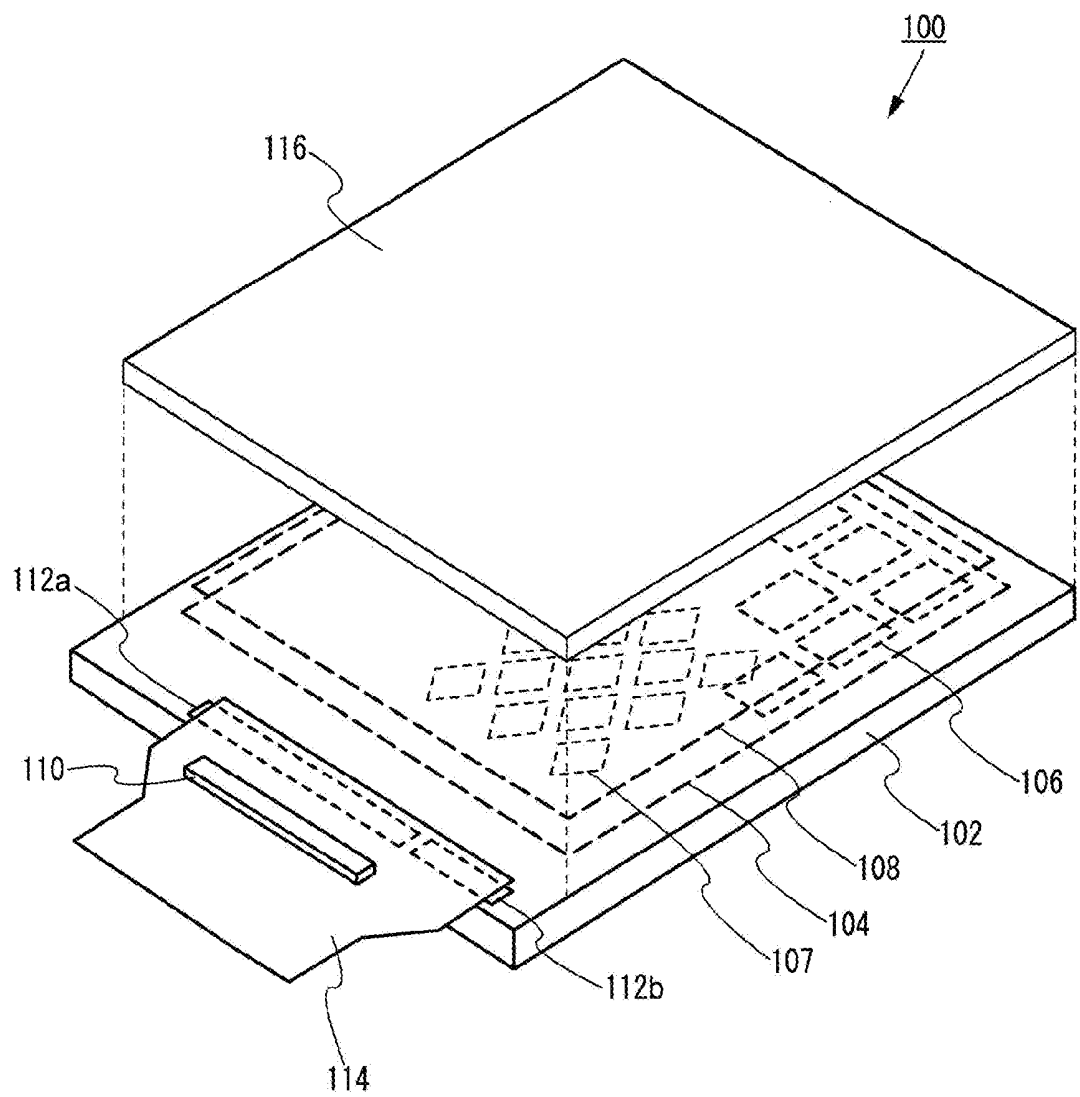


FIG. 2

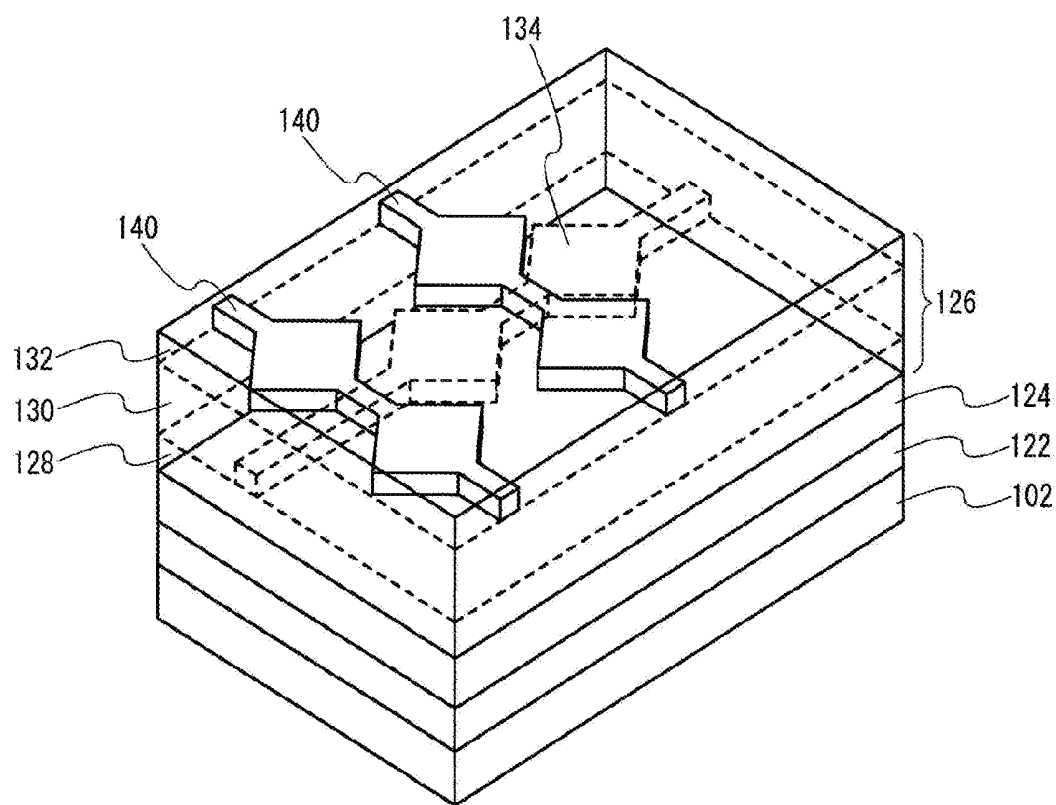


FIG. 3

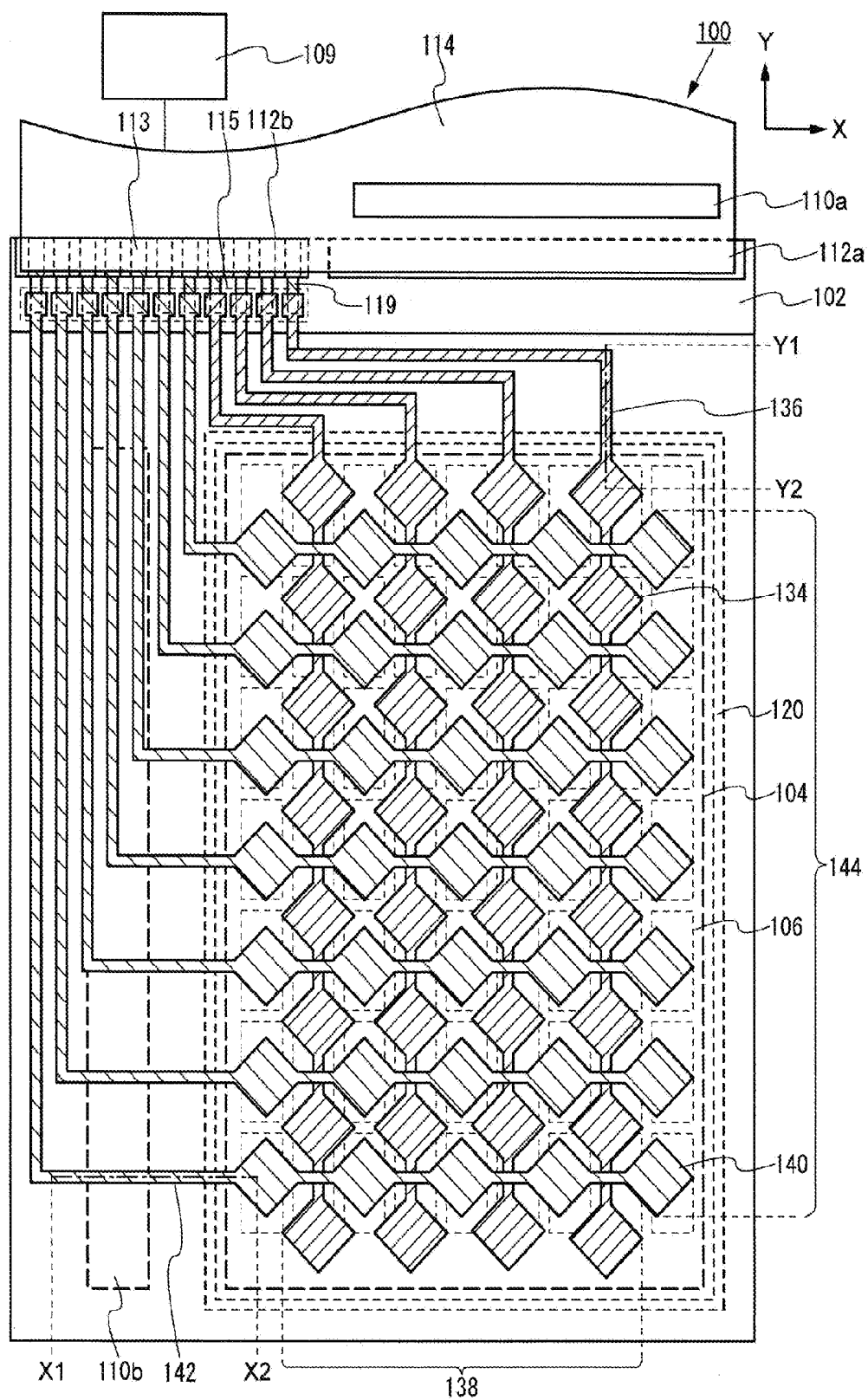


FIG. 4

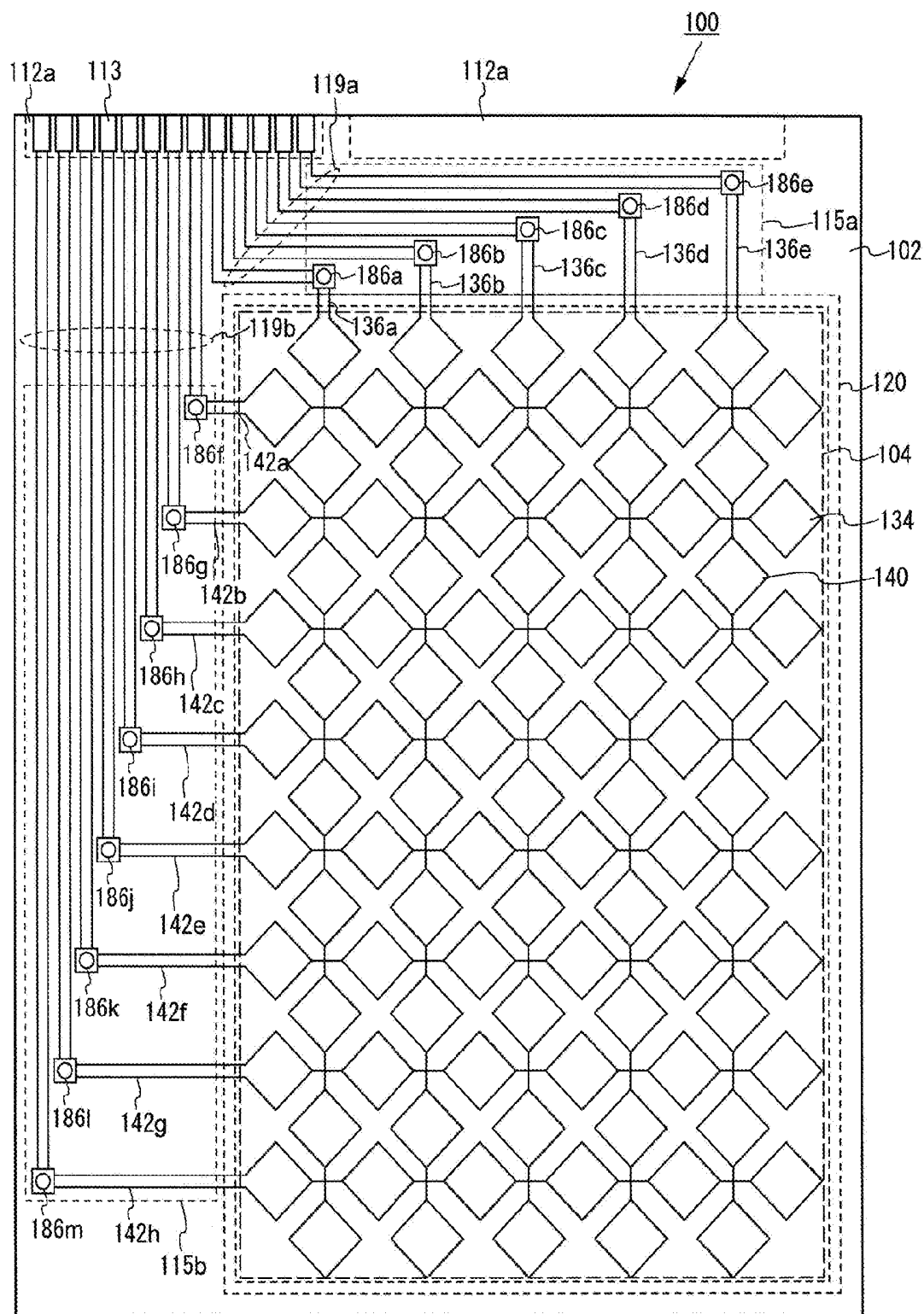


FIG. 5

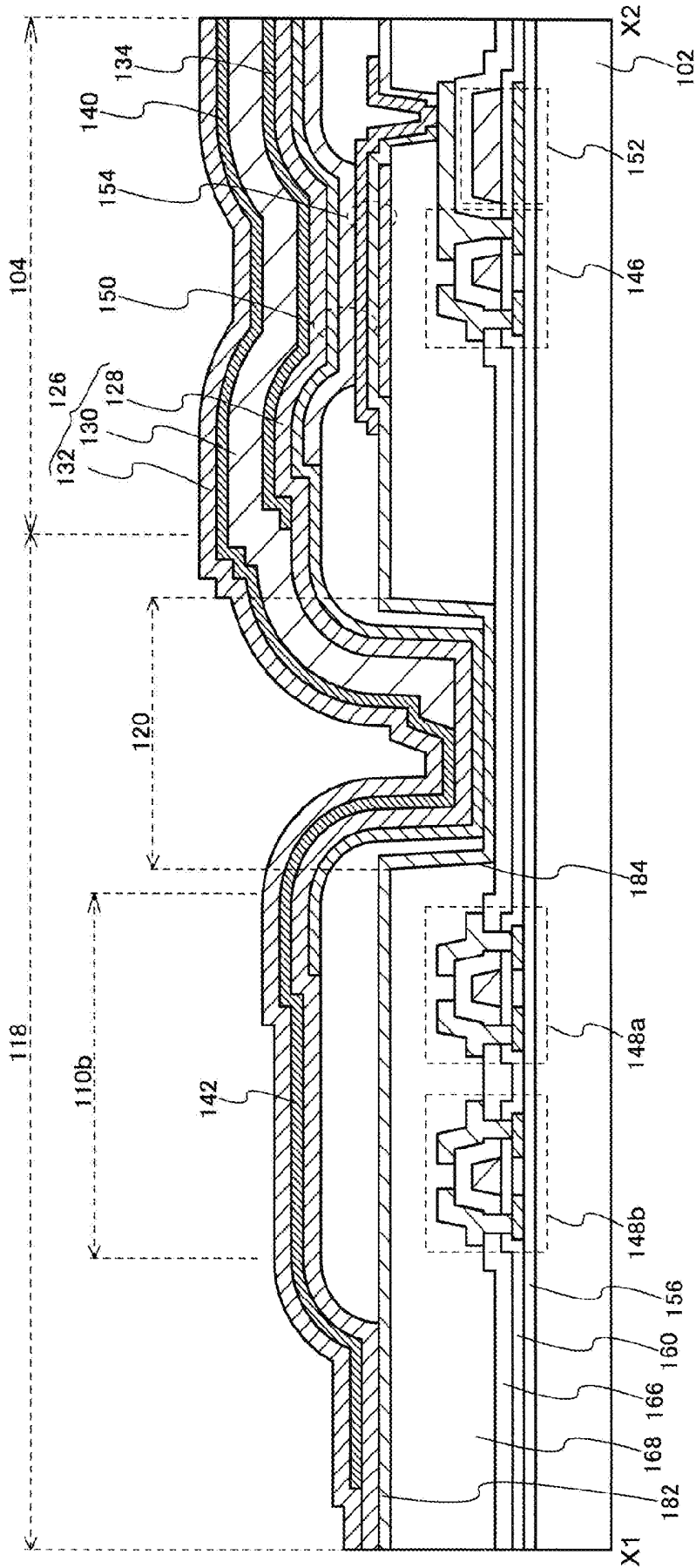


FIG. 6

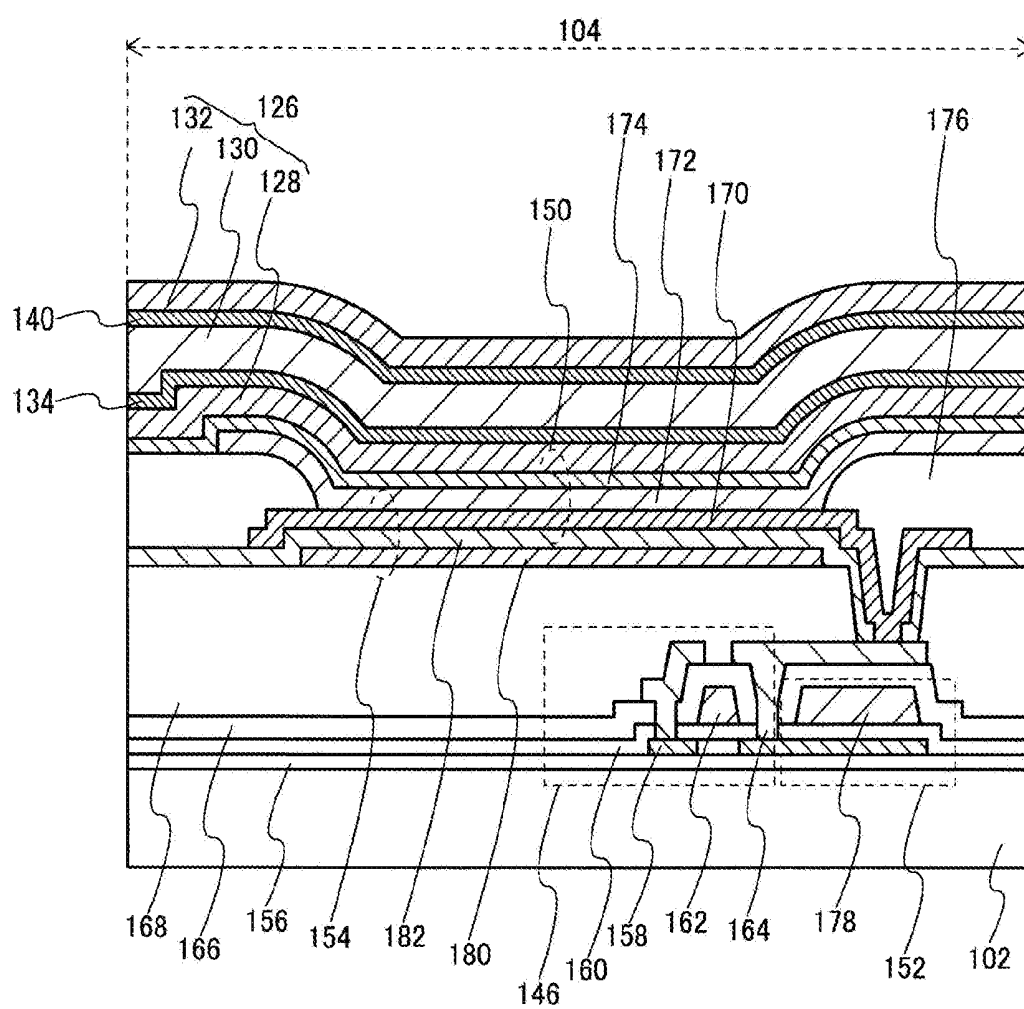


FIG. 7

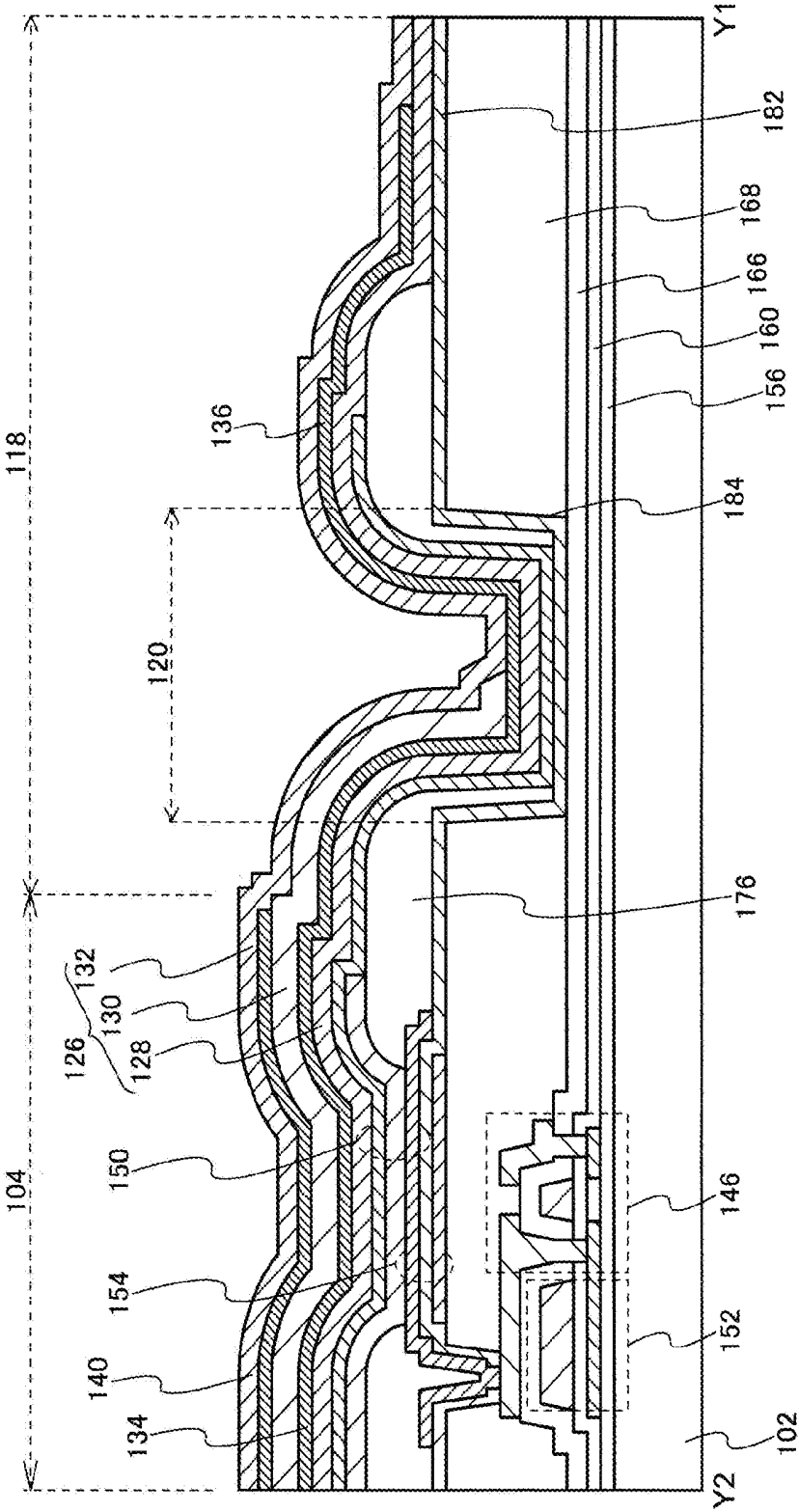


FIG. 8

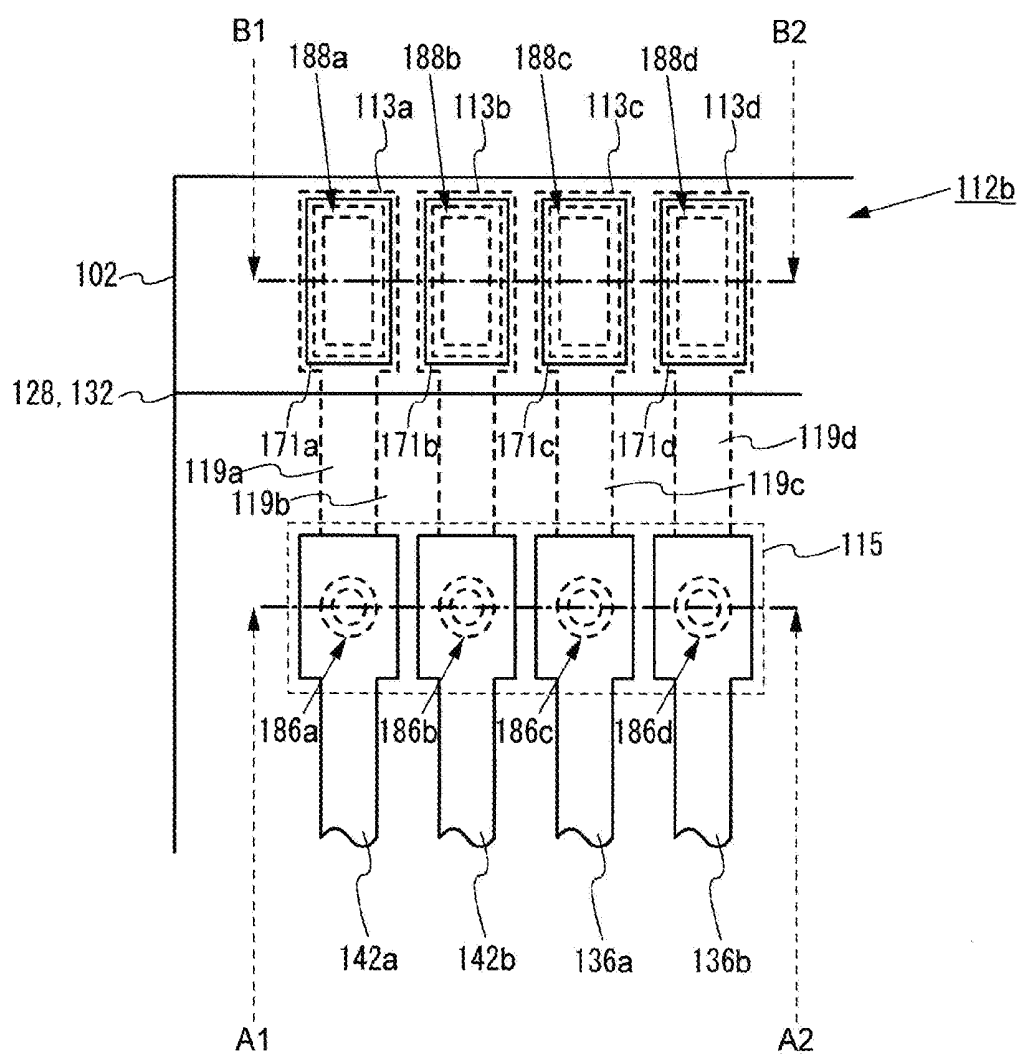


FIG. 9A

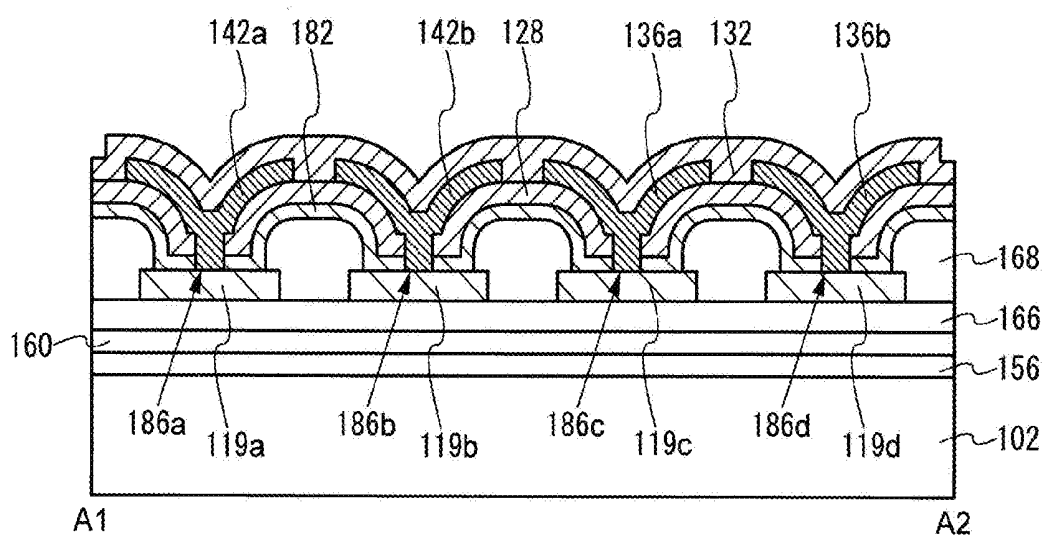
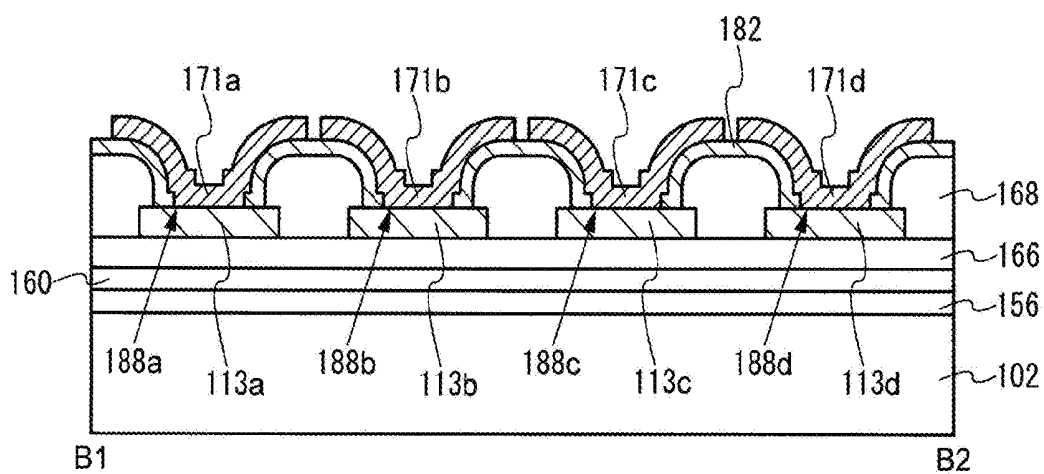


FIG. 9B



DISPLAY DEVICE

CROSS REFERENCE TO RELATED APPLICATIONS

[0001] This application is based upon and claims the benefit of priority from the prior Japanese Patent Application No. 2016-167854, filed on Aug. 30, 2016, the entire contents of which are incorporated herein by reference.

FIELD

[0002] The present invention is related to a display device. One embodiment of the invention disclosed in the present specification is related to a wiring structure of a touch sensor arranged in a display device.

BACKGROUND

[0003] Electronic devices which are operated by touching an image such as an icon displayed on a screen are becoming widespread. Display devices which are used in such electronic devices are also called touch panels (or touch screens). An electrostatic capacitance type touch sensor is employed in a touch panel. An element which detects a change in electrostatic capacitance between a pair of sensor electrodes called a Tx electrode and Rx electrode as an input signal is included in an electrostatic capacitance type touch sensor.

[0004] A conventional touch panel includes a structure in which a touch sensor panel and display panel overlap each other. However, a structure in which two panels overlap each other increases the thickness of a display device which is a problem. For example, in a display device which curves or bends known as a flexible display, a structure in which a touch sensor panel and display panel overlap each other is the cause of obstruction to flexibility.

[0005] Therefore, a structure in which the function of a touch sensor is incorporated within a display panel is disclosed. For example, an in-cell type display device is disclosed in which a first detection electrode and a second detection electrode are arranged sandwiching an inorganic insulation film arranged as a sealing film in a display panel which uses an organic electroluminescence element (called an "organic EL element" herein), and a touch sensor is arranged within the panel (for example, refer to Japanese Laid Open Patent Publication No: 2015-050245).

[0006] When attempting to install a touch sensor in a display panel, wiring for a connection with detection electrodes is required which increases the number of wiring layers. Since it is necessary to protect a display element using a sealing layer in a display panel, it is necessary to arrange a connection structure without degrading the sealing capability of a sealing layer when connecting wiring with a detection electrode or when connecting wiring connected to a detection electrode with a terminal electrode.

SUMMARY

[0007] A display device in an embodiment according to the present invention includes a substrate having an insulation surface, a plurality of wirings above the insulation surface, an interlayer insulation layer covering the plurality of wirings, a light emitting element above the interlayer insulation layer, a first inorganic insulation layer covering the light emitting element, a first detection electrode extending in a first direction above the first inorganic insulation

layer, an organic insulation layer above the first inorganic insulation layer covering the first detection electrode, a second detection electrode extending in a second direction intersecting the first direction above the organic insulation layer, a second inorganic insulation layer above the organic insulation layer covering the second detection electrode, a first connection wiring electrically connecting the first detection electrode and one of the plurality of wirings, and a second connection wiring electrically connecting the second detection electrode and another one of the plurality of wirings.

[0008] A display device in an embodiment according to the present invention includes a plurality of wirings above a substrate having an insulation surface, an interlayer insulation layer covering the plurality of wirings, a pixel region arranged with a plurality of pixels including a light emitting element above the substrate having the insulation surface, a sealing layer over the interlayer insulation layer and covering the pixel region, a first detection electrode extending in a first direction and a second detection electrode extending in a second direction intersecting the first direction above the pixel region, a first connection wiring electrically connecting the first detection electrode and one of the plurality of wirings, and a second connection wiring electrically connecting the second detection electrode and another wire included in the plurality of wirings.

[0009] The sealing layer includes an organic insulation layer, a first inorganic insulation layer arranged on a lower layer side of the organic insulation layer, and a second inorganic insulation layer arranged on an upper layer side of the organic insulation layer, and one of the first detection electrode and the second detection electrode is arranged on an upper layer side of the organic insulation layer and the other is arranged on a lower layer side of the organic insulation layer, both being arranged sandwiching the organic insulation layer.

BRIEF DESCRIPTION OF DRAWINGS

[0010] FIG. 1 is a perspective view diagram showing a structure of a display device related to one embodiment of the present invention;

[0011] FIG. 2 is a perspective view diagram showing a structure of a pixel region of a display device related to one embodiment of the present invention;

[0012] FIG. 3 is a planar diagram showing a structure of a display device related to one embodiment of the present invention;

[0013] FIG. 4 is a planar diagram showing a structure of a display device related to one embodiment of the present invention;

[0014] FIG. 5 is a cross-sectional diagram showing a structure of a display device related to one embodiment of the present invention;

[0015] FIG. 6 is a cross-sectional diagram showing a structure of a pixel region of a display device related to one embodiment of the present invention;

[0016] FIG. 7 is a cross-sectional diagram showing a structure of a display device related to one embodiment of the present invention;

[0017] FIG. 8 is a planar diagram showing a structure of a display device related to one embodiment of the present invention;

[0018] FIG. 9A is a structure of a display device related to one embodiment of the present invention and shows a cross-section of a connection part; and

[0019] FIG. 9B is a structure of a display device related to one embodiment of the present invention and shows a cross-section of a terminal electrode.

DESCRIPTION OF EMBODIMENTS

[0020] Hereinafter, the embodiments of the present invention will be described while referencing the drawings. However, the present invention may be implemented in many different ways, therefore interpretation should not be limited to the content exemplified in the embodiments below. In order to provide a clearer description, some components of the drawings such as the width, thickness, shape, etc. of each part are represented schematically. These drawings are merely examples and do not limit the interpretation of the present invention. In this specification and each of the drawings, elements similar to previously described elements are marked with the same symbols (numbers followed by a, b, and the like) and detailed descriptions are omitted accordingly. Furthermore, characters labeled as “first” and “second” are symbols used to distinguish each element, and do not have any further meaning unless otherwise specified.

[0021] In this specification, when certain components or regions are described as being “above” or “below” other components or regions, as long as there are no limitations, it does not necessarily mean they are directly above or below. This description includes cases in which a component or region is located higher or lower than another component or region. In other words, other components or regions are located between the component or region being described and the component or region above or below. Further, in the description below, unless otherwise noted, in a cross-sectional view, the side on which the second substrate is located with respect to the substrate will be described as “above” and the other side will be described as “below.”

[0022] FIG. 1 is a perspective view diagram showing a structure of a display device 100 related to one embodiment of the present invention. The display device 100 is arranged with a pixel region 104 and a touch sensor 108 on one main surface of a substrate 102 having an insulation surface. The pixel region 104 is arranged with a plurality of pixels 106. The plurality of pixels 106 is arranged in a row direction and column direction for example in the pixel region 104. The touch sensor 108 is arranged overlapping the pixel region 104. In other words, the touch sensor 108 is arranged so as to overlap the plurality of pixels 106. The touch sensor 108 is arranged with a plurality of detection electrodes 107 in a matrix shape and each is connected in a row direction and column direction respectively. Furthermore, a pixel 106 and touch sensor 108 are represented schematically here and their size relationship is not limited to that described in FIG. 1.

[0023] The display device 100 includes a first terminal region 112a input with a video signal and the like, and a second terminal region 112b which inputs and outputs signals of the touch sensor 108. The first terminal region 112a and second terminal region 112b are arranged at one end part in one main surface of the substrate 102 having an insulation surface. The first terminal region 112a and second terminal region 112b are arranged with a plurality of terminal electrodes along an end part of the substrate 102 having an insulation surface. The plurality of terminal electrodes of

the first terminal region 112a and second terminal region 112b is connected to a flexible printed wiring substrate 114. A drive circuit 110 outputs a video signal to a pixel 106. The drive circuit 110 is attached to the one main surface of the substrate 102 or the flexible printed wiring substrate 114.

[0024] The substrate 102 having an insulation surface is formed by a member such as glass or plastic (polycarbonate, polyethylene terephthalate, polyimide and polyacrylate and the like). When the material of the substrate 102 is a plastic, it is possible to provide flexibility to the display device 100 by thinning the substrate. That is, it is possible to provide a flexible display by using a plastic substrate as the substrate 102.

[0025] A polarization plate 116 which includes a polarizer may be arranged above the pixel region 104 and touch sensor 108. For example, the polarization plate 116 is formed by a polarizer exhibiting circularly polarized light properties. The polarization plate 116 is formed from a film material including a polarizer. By arranging the polarization plate 116 overlapping the pixel region 104 it is possible to prevent glare (mirror like state) of a display screen.

[0026] Furthermore, although omitted in FIG. 1, a pixel 106 is formed including a display element and a circuit element. It is preferred that the touch sensor 108 is an electrostatic capacitance type and is formed by a first detection electrode (Tx wiring) and second detection electrode (Rx wiring). An interlayer insulation layer is arranged between the pixel region 104 and touch sensor 108 so that they do not electrically and mutually short-circuit.

[0027] FIG. 2 is a perspective view diagram showing the pixel region 104 and a structure of the touch sensor 108 arranged thereupon. As is shown in FIG. 2, the pixel region 104 includes a circuit element layer 122 arranged with a circuit element and a display element layer 124 arranged with a display element above the substrate 102. A sealing layer 126 including a detection electrode for a touch sensor is arranged above the display element layer 124. The sealing layer 126 is arranged to cover an upper side surface of a display region when the main surface on the viewer side is set as a top surface.

[0028] The circuit element layer 122 includes an interlayer insulation layer. The interlayer insulation layer insulates wiring arranged in different layers. The interlayer insulation layer includes at least one inorganic interlayer insulation layer and at least one organic interlayer insulation layer. The inorganic interlayer insulation is formed by an inorganic insulation material such as silicon oxide, silicon nitride, silicon oxynitride and aluminum oxide and the like. The organic interlayer insulation layer is formed by an organic insulation material such as acrylic and polyimide and the like. The circuit element layer 122 includes an active element such as a transistor, a capacitor, a passive element such as a resistor and wiring which links these elements, and these are arranged buried in the interlayer insulation layer.

[0029] The display element layer 124 includes a light emitting element or an element which exhibits electro-optical effects by application of a voltage as a display element. In the case where an organic EL element is used as a light emitting element, the display element layer 124 is formed including electrodes distinguished as an anode and cathode, an organic layer including an organic EL material and a partition wall layer having insulation properties which divides adjacent organic EL elements in a planar view. The

organic EL element is electrically connected with a transistor of the circuit element layer 122.

[0030] The sealing layer 126 includes a structure in which a plurality of insulation films is stacked. FIG. 2 shows a structure in which a first inorganic insulation layer 128, organic insulation layer 130 and second inorganic insulation layer 132 are stacked as the sealing layer 126. The sealing layer 126 has increased sealing capabilities by using a stacked structure combining different materials. For example, even if the first inorganic insulation layer 128 includes defects, the organic insulation layer 130 buries such defective parts and by further arranging the second inorganic insulation layer 132 it is possible to compensate for any degradation in sealing capabilities due to these defects. The second inorganic insulation layer 132 may be arranged so as to cover the entire surface of a pixel region 104 and to cover at least a part of a region on the outer side of a pixel region 104, and the first inorganic insulation layer 128 and second inorganic insulation layer 132 may be formed so as to cover a region further to the outside of the second inorganic insulation layer 132. In addition, the outer circumference end parts of the first inorganic insulation layer 128 and second inorganic insulation layer 132 do not always have to match.

[0031] The sealing layer 126 encloses at least one of or both of the first detection electrode 134 and second detection electrode 140 which form the touch sensor 108. The first detection electrode 134 is arranged extending in a first direction and the second detection electrode 140 is arranged extending in a second direction intersecting the first direction. Although it is possible to set the first direction to an arbitrary direction, for example, it is possible to set the first direction along a column direction corresponding to the arrangement of pixels. In this case, it is possible to set the second direction to a direction along an arrangement of pixels in a row direction. A plurality of first detection electrodes 134 and second detection electrodes 140 are arranged respectively. In the present embodiment, a group formed by a plurality of first detection electrodes 134 is called a first detection electrode pattern and a group formed by a plurality of second detection electrodes 140 is called a second detection electrode pattern. Furthermore, only a part of the first detection electrode 134 and second detection electrode 140 is shown in FIG. 2, and a plurality of these detection electrodes are arranged aligned across roughly the entire pixel region 104.

[0032] This type of first detection electrode 134 and second detection electrode 140 are arranged sandwiching an organic insulation layer 130 which forms at least the sealing layer 126. The first detection electrode 134 and second detection electrode 140 are insulated by the organic insulation layer 130. That is, the first detection electrode 134 is arranged on one surface side of the organic insulation layer 130 and the second detection electrode 140 is arranged on the other surface side. The first detection electrode 134 and second detection electrode 140 are insulated by being arranged sandwiching the organic insulation layer 130 and electrostatic capacitance is generated between both detection electrodes. The touch sensor 108 determines the presence of a touch by detecting a change in the electrostatic capacitance produced between the first detection electrode 134 and second detection electrode 140.

[0033] FIG. 3 shows a planar view diagram of a display device 100. FIG. 3 schematically shows the first detection

electrode 134 and second detection electrode 140. FIG. 3 shows a vertical direction as a Y direction and a horizontal direction as an X direction with respect to the page surface for the convenience of explanation.

[0034] In FIG. 3, a plurality of first detection electrodes 134 extend in the Y direction and a plurality of second detection electrodes 140 extend in the X direction. Here, a group of a plurality of first detection electrodes 134 is set as a first detection electrode pattern 138 and a group of a plurality of second detection electrodes 140 is set as a second detection electrode pattern 144.

[0035] Furthermore, the shape of the first detection electrode 134 and the second detection electrode 140 is arbitrary. The first detection electrode 134 and the second detection electrode 140 may have a rectangular (stripe) shape or may have a diamond shape as is shown in FIG. 3. By adopting a detection electrode having such a stripe shape or diamond shape, an improvement in detection sensitivity of the touch sensor 108 is achieved.

[0036] The first detection electrode pattern 138 and the second detection electrode pattern 144 are arranged in a region overlapping the pixel region 104. In other words, the first detection electrode and second detection electrode are arranged to overlap at least a part (part of a light emitting element arranged in a pixel) of a pixel 106. By adopting such an arrangement, it is possible to sense the presence of a touch with the touch sensor 108 while continuing to display an image such as an icon and the like in the display region 104.

[0037] The first detection electrode 134 is electrically connected with first connection wiring 136 arranged on the outer side of the pixel region 104. The first connection wiring 136 is electrically connected with wiring 119 arranged corresponding to a terminal electrode of the second terminal region 112b. The first connection wiring 136 extends towards an end part where the terminal region 112 of the substrate 102 is arranged and further curves extending to the connection part 115. A plurality of wirings 119 is arranged each corresponding to a terminal electrode 113 arranged in the second terminal region 112b. The plurality of wirings 119 extends from a connection part with the first connection wiring 136 towards to the second terminal region 112b. That is, the first detection electrode 134 and a terminal electrode of the second terminal region 112b are electrically connected by the first connection wiring 136 and wiring 119.

[0038] The second detection electrode 140 is electrically connected with the second connection wiring 142 arranged on the outer side of the pixel region 104. The second connection wiring 142 extends from the pixel region 104 towards one side edge of the substrate 102, and further bends and extending to the second terminal region 112b along this side edge. In addition, the second connection wiring 142 is arranged corresponding to a terminal electrode of the second terminal region 112b and is electrically connected with a plurality of wirings 119 extending from a connection part with the second connection wiring 142 towards the second terminal region 112b.

[0039] That is, the second detection electrode 140 and a terminal electrode of the second terminal region 112b are electrically connected by the second connection wiring 142 and wiring 119. The second connection wiring 142 may also be arranged in a region overlapping a region where a drive circuit 110b is arranged in the substrate 102. The frame of a

display panel can be narrowed by overlapping the second connection wiring 142 with the drive circuit 110b.

[0040] Furthermore, a plurality of terminal electrodes 113 of the second terminal region 112b is arranged along the end part of the substrate 102. The wiring 119 is arranged corresponding to each terminal electrode 113. The wiring 119 extends from the terminal electrode 113 to an inner side region of the substrate 102. The wiring 119 which is connected with a terminal electrode 113 of the second terminal region 112b is arranged at least on a lower layer side sandwiching at least one interlayer insulation layer with respect to the first connection wiring 136 and second connection wiring 142. The first connection wiring 136 and second connection wiring 142 are connected at the connection part 115. In the connection part 115, wiring 119 of a lower layer side is electrically connected with the first connection wiring 136 and second connection wiring 142 via a contact hole 186 arranged in an insulation layer in the connection part 115.

[0041] An opening region 120 is arranged in the substrate 102 enclosing the pixel region 104. In other words, an interlayer insulation layer above the substrate 102 includes at least one inorganic interlayer insulation layer and organic interlayer insulation layer and includes a stacked layer region in which an inorganic interlayer insulation layer and organic interlayer insulation layer are stacked and an opening region where an organic interlayer insulation layer is removed and an inorganic interlayer insulation layer is remains. The opening region 120 is explained in detail using a cross-sectional structure of the pixel region 104 described herein. The first connection wiring 136 and second connection wiring 142 are extracted from the pixel region 104 to a periphery edge part of the substrate 102 passing above the opening region 120.

[0042] The second terminal region 112b is connected with a touch sensor control part 109 via a flexible printed wiring substrate 114. That is, a detection signal obtained from the first detection electrode 134 and second detection electrode 140 is transmitted to the second terminal region 112b via the first connection wiring 136 and second connection wiring 142 and also the wiring 119, and is output to the touch sensor control part 109 via the flexible printed wiring substrate 114.

[0043] FIG. 3 shows an example in which a connection part between the first connection wiring 136, second connection wiring 142 and the wiring 119 is arranged in the vicinity of the second terminal region 112b. On the other hand, FIG. 4 shows another form of the connection part 115. First connection wirings 136a-136e extend towards an end part where the terminal region 112 of the substrate 102 is arranged. One end of the plurality of wirings 119 extends as far as the first connection wirings 136a-136e along an end part of the substrate 102 arranged with the terminal region 112. In addition, the plurality of wirings 119a and the first connection wirings 136a-136e are connected to each other through the contact holes 186a-186e at region where the wirings 119a and the first connection wirings 136a-136e intersect each other. The connection part 115a is arranged with the contact holes 186a-186e along a side edge of the substrate 102. Second connection wirings 142a-142e extend toward one side end part of the substrate 102. One part of a plurality of wirings 119 extends as far as the second connection wirings 142a-142e along this one side end part. In addition, the plurality of wirings 119b and the first connection wirings 142a-142e are connected to each other through

the contact holes 186f-186m at region where the wirings 119b and the first connection wirings 142a-142e intersect each other. The connection part 115b is arranged with the contact holes 186f-186m along one side end part of the substrate 102. The contact holes 186a-186m arranged in an interlayer insulation layer are all arranged on an outer side of the opening region 120 at the connection parts 115a, 115b. Since a plurality of wirings 119 is wiring on a lower layer side buried in an interlayer insulation layer, it is possible to miniaturize the wiring 119 compared with the first connection wiring 136 and second connection wiring 142. As a result, it is possible to narrow the width of a wiring region arranged as far as the second terminal region 112b.

[0044] The display device 100 related to one embodiment of the present invention is arranged with the first detection electrode pattern 138 and second detection electrode pattern 144 which form the touch sensor 108 above the substrate 102. Since it is not necessary to externally attach a touch sensor arranged as a separate product with this structure, it is possible to achieve a thin display device 100. As is shown in FIG. 2, the first detection electrode 134 and second detection electrode 140 are arranged to be buried in the sealing layer 126 or contacting the sealing layer 126. Since a dielectric layer for forming electrostatic capacitance between the first detection electrode 134 and second detection electrode 140 is replaced with a part of the sealing layer 126 with this structure, it is possible to achieve an even thinner display device 100.

[0045] FIG. 5 shows a cross-sectional structure of the display device 100 related to one embodiment of the present invention. FIG. 5 schematically shows a cross-sectional structure of the pixel region 104 and a periphery region 118 located on the outer side of the pixel region 104. This cross-sectional structure corresponds to the structure along the line X1-X2 shown in FIG. 3.

[0046] As is shown in FIG. 5, the pixel region 104 and periphery region 118 are arranged above the substrate 102. The periphery region 118 includes the opening region 120 and drive circuit 110b. The pixel region 104 includes a transistor 146, organic EL element 150, first capacitor element 152 and second capacitor element 154. Details of these elements are shown in FIG. 6.

[0047] As is shown in FIG. 6, the organic EL element 150 is electrically connected with the transistor 146. A current flowing between the source and drain of the transistor 146 is controlled by a video signal applied to the gate and light emitting luminosity of the organic EL element 150 is controlled by this current. The first capacitor element 152 stores a gate voltage of the transistor 146 and the second capacitor element 154 is arranged for adjusting the amount of current flowing to the organic EL element 150. Furthermore, the second capacitor element 154 is not essential and can be omitted.

[0048] A base insulation layer 156 is arranged on a first surface of the substrate 102. The transistor 146 is arranged above the base insulation layer 156. The transistor 146 has a structure in which a semiconductor layer 158, gate insulation layer 160 and gate electrode 162 are stacked. The semiconductor layer 158 is formed from amorphous or polycrystalline silicon or an oxide semiconductor material and the like. A source/drain wiring 164 is arranged on an upper layer of the gate electrode 162 via a first insulation

layer **166**. A second insulation layer **168** is arranged as a leveling layer on an upper layer of the source/drain wiring **164**.

[0049] The first insulation layer **166** and the second insulation layer **168** are interlayer insulation layers. The first insulation layer **166** is a type of inorganic interlayer insulation layer and is formed from an inorganic insulation material such as silicon oxide, silicon nitride, silicon oxynitride or aluminum oxide and the like. The second insulation layer **168** is a type of organic interlayer insulation layer and is formed from an organic insulation material such as polyimide or acrylic and the like. An interlayer insulation layer is stacked with the first insulation layer **166** and second insulation layer **168** in order from the substrate **102** side. By arranging the second insulation layer **168** formed from an organic insulation material on an upper layer of the first insulation layer **166**, concave and convex parts caused by the transistor **146** and the like are buried and the surface is leveled.

[0050] The organic EL element **150** is arranged on an upper surface of the second insulation layer **168**. The organic EL element **150** has a structure in which a pixel electrode **170** electrically connected with the transistor **146**, an organic layer **172** and a counter electrode **174** are stacked. The organic EL element **150** is a two-terminal element and light emission is controlled by controlling a voltage between the pixel electrode **170** and counter electrode **174**. A partition wall layer **176** is arranged above the second insulation layer **168** so as to cover a periphery edge part of the pixel electrode **170** and expose an inner side region. The counter electrode **174** is arranged on an upper surface of the organic layer **172**. The organic layer **172** is arranged from a region which overlaps the pixel electrode **170** to an upper surface part of the partition wall layer **176**. The partition wall layer **176** is formed from an organic resin material in order to both cover a periphery edge part of the pixel electrode **170** and to form a smooth step at an end part of the pixel electrode **170**. Acrylic or polyimide and the like is used as the organic resin material.

[0051] The organic layer **172** is formed of a single layer or a plurality of layers including an organic EL material. The organic layer **172** is formed using a low molecular or high molecular organic material. In the case where a low molecular organic material is used, the organic layer **172** is formed including a hole injection layer, an electron injection layer, a hole transport layer, an electron transport layer and the like in addition to the light emitting layer containing an organic EL material. For example, the organic layer **172** can have a structure in which a light emitting layer is sandwiched between a hole injection layer and an electron injection layer. In addition to the hole injection layer and the electron injection layer, a hole transport layer, an electron transport layer, a hole block layer and an electron block layer and the like may be appropriately added to the organic layer **172**.

[0052] Furthermore, in this embodiment the organic EL element **150** has a so-called top emission type structure in which light emitted by the organic layer **172** is radiated toward the counter electrode **174** side. As a result, it is preferred that the pixel electrode **170** has light reflectivity. In addition to the pixel electrode **170** being formed by a light reflective metal material such as aluminum (Al) or silver (Ag), the pixel electrode **170** may have a structure in which a transparent conductive layer formed from ITO (Indium Tin

Oxide) or IZO (Indium Zinc Oxide) which have excellent hole injection properties, and a light-reflective metal layer are stacked.

[0053] The counter electrode **174** is formed from a transparent conductive film such as ITO or IZO which have translucency and conductivity in order to allow light emitted from the organic layer **172** to pass through. A layer containing an alkali metal such as lithium or an alkaline earth metal such as magnesium may be arranged at the interface between the counter electrode **174** and the organic layer **172** in order to increase carrier injection properties.

[0054] The first capacitor element **152** is formed in a region where the semiconductor layer **158** and the first capacitor electrode **178** overlap using the gate insulating layer **160** as a dielectric film. In addition, the second capacitor element **154** is formed by the pixel electrode **170** and a second capacitor electrode **180** overlapping the pixel electrode using a third insulating layer **182** arranged between the pixel electrode **170** and the second capacitor electrode **180** as a dielectric film. The third insulating layer **182** is formed by an inorganic insulation material such as silicon nitride.

[0055] The sealing layer **126** is arranged on an upper layer of the organic EL element **150**. The sealing layer **126** is arranged to prevent moisture and the like from entering the organic EL element **150**. The sealing layer **126** has a structure in which a first inorganic insulation layer **128**, an organic insulation layer **130** and a second inorganic insulation layer **132** are stacked from the organic EL element **150** side. The first inorganic insulation layer **128** and the second inorganic insulation layer **132** are formed from an inorganic insulation material such as silicon nitride, silicon nitride oxide and aluminum oxide or the like. The first inorganic insulation layer **128** and the second inorganic insulation layer **132** are formed by depositing these inorganic insulation materials using a sputtering method or a plasma CVD method, or the like. The first inorganic insulation layer **128** and the second inorganic insulation layer **132** are formed to a thickness of 0.1 μm to 10 μm , and preferably 0.5 μm to 5 μm .

[0056] Furthermore, as is shown in FIG. 8 described herein, the first inorganic insulation layer **128** and the second inorganic insulation layer **132** are preferably formed by depositing on the entire surface of the substrate **102** in order to expose a region of the second terminal region **112b** and then patterning by photolithography or ensuring that an insulation film is not formed at least in the second terminal region **112b** using a mask (a metal mask having an opening part on the film formation surface).

[0057] It is preferred that the organic insulation layer **130** is formed of acrylic resin, polyimide resin, epoxy resin, or the like. The organic insulation layer **130** is arranged with a thickness of 1 μm to 20 μm , and preferably 2 μm to 10 μm . The organic insulation layer **130** is formed by a coating method such as spin coating or an evaporation method using an organic material source. The organic insulation layer **130** is formed in a predetermined region including the pixel region **104** so as to both cover the pixel region **104** and to seal the end part with the first inorganic insulation layer **128** and the second inorganic insulation layer **132**. For example, it is preferred that the end part (contour part) of the organic insulation layer **130** is arranged between the pixel region **104** and the opening region **120** or at a position overlapping the opening region **120**. As a result, after forming the organic

insulation layer 130 on the entire surface of the substrate 102 by a coating method, either the outer periphery region is removed by etching or formed into a predetermined pattern in advance by an evaporation method (mask evaporation) using a mask that opens the deposition target surface, inkjet printing, flexographic printing or gravure printing.

[0058] Furthermore, although omitted in FIG. 6, a polarization plate 116 is arranged on the upper surface of the sealing layer 126 as shown in FIG. 1. In addition to a polarizer, the polarization plate 116 may also include a color filter layer and a light shielding layer as appropriate.

[0059] The first detection electrode 134 of the touch sensor 108 is arranged between the first inorganic insulation layer 128 and the organic insulation layer 130 and the second detection electrode 140 is arranged between the organic insulation layer 130 and the second inorganic insulation layer 132. The first detection electrode 134 and the second detection electrode 140 are preferably formed from a transparent conductive film in order to allow light emitted from the organic EL element 150 to pass through. Coatings of ITO and IZO which are one type of transparent conductive film are produced by a sputtering method. In addition, the first detection electrode 134 and the second detection electrode 140 may be produced by a printing method using silver nanowires.

[0060] In the present embodiment, since the organic insulation layer 130 is formed on an upper layer of the first detection electrode 134, even if foreign objects are adhered after forming the transparent conductive film forming the first detection electrode 134, the foreign objects can be coated with the organic insulation layer 130. In this way, short circuits between the second detection electrode 140 formed on the organic insulation layer 130 and the first detection electrode 134 can be prevented. Furthermore, since the second inorganic insulation layer 132 is arranged on an upper layer of the organic insulation layer 130 (upper layer of the second detection electrode 140), a function as the sealing layer 126 can be maintained.

[0061] In FIG. 5, the driving circuit 110b included in the periphery region 118 on the outer side of the pixel region 104 is arranged with transistors 148a and 148b. For example, the transistor 148a is an n channel transistor and the transistor 148b is a p channel transistor. A drive circuit is formed by such transistors.

[0062] The opening region 120 is arranged between the pixel region 104 and the drive circuit 110b. The opening region 120 includes an opening part 184 which passes through the second insulation layer 168. The opening part 184 is arranged along at least one side of the pixel region 104. Preferably, the opening part 184 is arranged so as to surround the pixel region 104. The second insulation layer 168 is divided into a pixel region 104 side and a drive circuit 110b side by the opening part 184. In addition, the partition wall layer 176 is also divided at the opening part 184. In other words, the second insulation layer 168 and the partition wall layer 176 formed from an organic material are removed in the opening part 184. The third insulation layer 182 and the counter electrode 174 arranged on the upper surface of the partition wall layer 176 are arranged along the side surface and the bottom surface of the opening part 184.

[0063] An end part of the organic insulation layer 130 forming the sealing layer 126 is arranged in the opening part 184. The first inorganic insulation layer 128 and the second inorganic insulation layer 132 extend to the outer side of the

end part of the organic insulation layer 130. In this way, a structure in which the first inorganic insulation layer 128 and the second inorganic insulation layer 132 are in contact with each other is formed in the outer side region of the organic insulation layer 130. In other words, the organic insulation layer 130 is sandwiched between the first inorganic insulation layer 128 and the second inorganic insulation layer 132, and has a structure in which the end part is not exposed. With this structure, it is possible to prevent moisture or the like from entering from the end part of the organic insulation layer 130.

[0064] Furthermore, the end part of the organic insulation layer 130 may be located outside the pixel region 104. However, by overlapping the end part with the opening part 184, a region can be arranged in the opening region 120 in which the first insulation layer 166, the third insulation layer 182, the counter electrode 174, the first inorganic insulation layer 128, the second connection wiring 142, and the second inorganic insulation layer 132 are stacked. With such a stacked structure, sealing capabilities can be increased.

[0065] In this way, a sealing structure is formed by dividing the second insulation layer 168 and the partition wall layer 176 formed from an organic insulation material in the periphery region 118 by the opening part 184, and by arranging the third insulation layer 182 and the counter electrode 174 formed from an inorganic material so as to cover the side surface and the bottom surface of the opening part 184. The third insulation layer 182 is arranged in close contact with the first insulation layer 166 formed from an inorganic material at the bottom part of the opening part 184. By sandwiching the second insulation layer 168 and the partition wall layer 176 formed from an organic insulating material between inorganic material layers, it is possible to prevent moisture from entering the pixel region 104 from the end part of the substrate 102. A region in which the opening part 184 for separating the second insulation layer 168 and the partition wall layer 176 is arranged can function as a moisture blocking region and its structure can be called a "moisture blocking structure".

[0066] The second connection wiring 142 which is connected to the second detection electrode 140 passes through the opening region 120 and is arranged above the drive circuit 110b. As is shown in FIG. 3, the second connection wiring 142 extends from the pixel region 104 toward one side edge of the substrate 102 and extends along the one side edge so as to be connected to the second terminal region 112b.

[0067] An insulation layer is arranged on an extended part where the second connection wiring 142 extends toward the second terminal region 112b. A base insulation layer 156, a gate insulating layer 160, a first insulation layer 166, a second insulation layer 168, and a third insulation layer 182 are arranged from the substrate 102 side on a lower layer side of the second connection wiring 142. Although an insulation layer can be omitted such as the base insulation layer 156 among these insulation layers, by arranging at least the second insulation layer 168 as a leveling layer on the lower layer side of the second connection wiring 142, it is insulated from the wiring of the driving circuit 110b. The second connection wiring 142 is arranged sandwiched between the first inorganic insulation layer 128 and the second inorganic insulation layer 132 above the second insulation layer 168. In this way, the second connection

wiring **142** is protected by the first inorganic insulation layer **128** and the second inorganic insulation layer **132**.

[0068] FIG. 7 shows a cross-sectional structure corresponding to the line Y1-Y2 shown in FIG. 3. The pixel region **104** and the periphery region **118** are also shown in FIG. 7. The periphery region **118** includes the opening region **120**. In the opening region **120**, a region is included in the opening part **184** in which the first insulation layer **166**, the third insulation layer **182**, the counter electrode **174**, the first inorganic insulation layer **128**, the second detection electrode **140**, and the second inorganic insulation layer **132** are stacked. The first connection wiring **136** connected to the first detection electrode **134** is arranged along an upper surface of the first inorganic insulation layer **128** and extends beyond the opening region **120** toward the end part side of the substrate **102**.

[0069] An insulating layer is arranged on the extended part where the first connection wiring **136** extends toward the second terminal region **112b**. Similar to the second connection wiring **142**, the base insulation layer **156**, the gate insulation layer **160**, the first insulation layer **166**, the second insulation layer **168**, and the third insulation layer **182** are arranged on a lower layer side of the first connection wiring **136** from the substrate **102** side. The first connection wiring **136** is arranged sandwiched between the first inorganic insulation layer **128** and the second inorganic insulation layer **132** above the second insulation layer **168**. In this way, the first connection wiring **136** is protected by the first inorganic insulation layer **128** and the second inorganic insulation layer **132**. The first connection wiring **136** is arranged sandwiched between the first inorganic insulation layer **128** and the second inorganic insulation layer **132**. In this way, the first connection wiring **136** is protected by the first inorganic insulation layer **128** and the second inorganic insulation layer **132**.

[0070] Details of the terminal region **112** and the connection part **115** shown in FIG. 3 are shown in FIG. 8, FIG. 9A, and FIG. 9B. FIG. 8 is a planar view of a terminal electrode **113** and connection part **115**, and FIG. 9A shows a cross-sectional structure corresponding to the line A1-A2 in the drawing, and FIG. 9B shows a cross-sectional structure corresponding to the line B1-B2. In the explanation below, an explanation is given while referring to FIG. 8, FIG. 9A, and FIG. 9B as appropriate.

[0071] In the second terminal region **112b**, terminal electrodes **113a-113d** are arranged along an end part of the substrate **102**, and wirings **119a-119d** are arranged corresponding to each terminal electrode. The terminal electrodes **113a-113d** are electrically connected to the wirings **119a-119d**. The wirings **119a-119d** extend from the terminal electrodes **113a-113d** to the connection part **115**. Second connection wirings **142a** and **142b** and first connection wirings **136a** and **136b** are arranged corresponding to the arrangement of the wirings **119a-119d**.

[0072] The terminal electrodes **113a-113d** are formed by the same conductive layer as the source/drain wiring **164** for example. The terminal electrodes **113a-113d** are covered by an upper insulation layer similar to the source/drain wiring **164**. For example, the terminal electrodes **113a-113d** are covered by the second insulation layer **168** and the third insulation layer **182** as an upper layer insulation layer. The first inorganic insulation layer **128** and the second inorganic insulation layer **132** are arranged so as not to cover the terminal electrodes **113a-113d**. That is, the end parts of the

first inorganic insulation layer **128** and the second inorganic insulation layer **132** are arranged further to the inner side than the end of the substrate **102**. The first inorganic insulation layer **128** and the second inorganic insulation layer **132** are arranged so as not to cover the terminal electrodes **113a-113d**. That is, the end parts of the first inorganic insulation layer **128** and the second inorganic insulation layer **132** are arranged further to the inner side than the end part of the substrate **102**.

[0073] Upper surface parts of the terminal electrodes **113a-113d** are exposed by opening parts **188a-188d** from which an upper layer insulation layer is removed at the connection part with the flexible printed wiring substrate **114**. The opening parts **188a-188d** are regions where an opening part arranged in the second insulation layer **168** overlaps with an opening part arranged in the third insulation layer **182**. The open end of the opening part of the second insulation layer **168** and the open end of the opening part of the third insulation layer **182** may match with each other or as is shown in FIG. 9B, the open end of the opening part of the third insulation layer **182** may be arranged further to the inner side than the open end of the opening part in the second insulation layer **168**. As is shown in FIG. 9B, a side end part of the open part of the second insulation layer **168** formed from an organic insulating material is covered by the third insulation layer **182** formed using an inorganic insulation material, thereby it is possible to prevent moisture or the like from entering from the side end part of the opening part of the second insulation layer **168**.

[0074] The first inorganic insulation layer **128** and the second inorganic insulation layer **132** include the opening region **120** and are arranged on roughly the entire surface excluding one part of the substrate **102**. The end parts of the first inorganic insulation layer **128** and the second inorganic insulation layer **132** are located in a region further to the inner side than the terminal electrodes **113a-113d** which is an inner side region which does not reach the end part of the substrate **102** so that the opening parts **188a-188d** are not buried in a region of the second terminal region **112b**. This also applies to the first terminal region **112a**. Oxide conductive films **171a-171d** are arranged in parts where the terminal electrodes **113a-113d** are exposed by the opening parts **188a-188d**. The oxide conductive films **171a-171d** are formed, for example, using the same layer as the conductive layer forming the pixel electrode **170**. Although the oxide conductive films **171a-171d** are not essential, they are preferably arranged in order to protect the surfaces of the terminal electrodes **113a-113d** and to prevent an increase in contact resistance due to oxidation.

[0075] As is shown in FIG. 9A, the wirings **119a-119d**, the first connection wirings **136a** and **136b**, and the second connection wirings **142a** and **142b** are respectively connected via contact holes **186a-186d**. The contact holes **186a-186d** are formed in a region where opening parts formed by a through hole arranged in the second insulation layer **167**, a through hole arranged in the third insulation layer **182**, and a through hole arranged in the first inorganic insulation layer **128** overlap. A base insulation layer **156**, a gate insulation layer **160**, and a first insulation layer **166** are stacked on a lower layer of the terminal electrodes **113a-113d**. The first connection wirings **136a** and **136b** and the second connection wirings **142a** and **142b** are arranged with the first inorganic insulation layer **128** on a lower layer side

and the second inorganic insulation layer **132** on an upper layer side in the connection part **115**.

[0076] The first inorganic insulation layer **128** and the second inorganic insulation layer **132** are insulation films which have high barrier properties against moisture such as silicon nitride, silicon oxynitride, and aluminum oxide or the like. The first connection wirings **136a** and **136b** and the second connection wirings **142a** and **142b** are insulated in the periphery region **118** by being sandwiched between the first inorganic insulation layer **128** and the second inorganic insulation layer **132** which prevent corrosion due to the influence of moisture or the like. Furthermore, since the contact holes **186a-186d** are arranged on the outer side of the opening region **120** as shown in FIG. 3, even if through holes are arranged in the first inorganic insulation layer **128**, moisture does not penetrate to the inner side of the sealing layer **126**.

[0077] In the sealing layer **126**, an end part of the organic insulation layer **130** is not arranged further to the outer side than the opening region **120** as shown in FIG. 5 and FIG. 7. That is, an end part of the organic insulation layer **130** is located further to the inner side than an end part of the first inorganic insulation layer **128** and the second inorganic insulation layer **132**, and is arranged inside the contact hole **186**. In this way, the end part of the organic insulation layer **130** which forms the sealing layer **126** has a structure that is not exposed to the exterior even by the region where the contact hole **186** is formed, so that entry of moisture or the like can be prevented. In this way, the sealing layer **126** can prevent deterioration of sealing capabilities.

[0078] As shown in FIG. 9A, the first connection wiring **136** connected to the first detection electrode **134** and the second connection wiring **142** connected to the second detection electrode **140** are extracted to the outer side of the organic insulation layer **130** which forms the sealing layer **126**, and connected to the wiring on a lower layer side (for example, wiring formed using the same layer as a source/drain electrode), thereby it is possible to ensure an electrical connection. In other words, the first connection wiring **136** connected to the first detection electrode **134** and the second connection wiring **142** connected to the second detection electrode **140** are sealed by the first inorganic insulation layer **128** and the second inorganic insulation layer **132** outside the opening region **120** up to a region reaching the connection part **115**, thereby the reliability of a touch sensor can be improved.

[0079] As is shown in FIG. 5 and FIG. 7, by arranging the first detection electrode **134** and second detection electrode **140** via the organic insulation layer **130**, short-circuits are prevented even in the case where foreign objects remain. In addition, by arranging the first connection wiring **136** which is connected to the first detection electrode **134** and second connection wiring **142** which is connected to the second detection electrode **140** each sandwiched by the first inorganic insulation layer **128** and second inorganic insulation layer **132**, and pulling the wiring in different directions in the substrate **102**, both wirings are insulated. By adopting such a structure, short circuits of detection electrodes and wiring which form a touch sensor are securely prevented.

[0080] Furthermore, according to the present embodiment, since the first detection electrode **134** and second detection electrode **140** are internally arranged in the sealing layer **126** sandwiching the organic insulation layer **130**, it is possible to make a thin display device **100**. This type of structure can

also be applied to a sheet shaped substrate in which the substrate **102** is formed with an organic resin material and can realize a flexible display installed with a touch panel.

What is claimed is:

1. A display device comprising:

- a substrate having an insulation surface;
- a plurality of wirings above the insulation surface;
- an interlayer insulation layer covering the plurality of wirings;
- a light emitting element above the interlayer insulation layer;
- a first inorganic insulation layer covering the light emitting element;
- a first detection electrode extending in a first direction above the first inorganic insulation layer;
- an organic insulation layer above the first inorganic insulation layer covering the first detection electrode;
- a second detection electrode extending in a second direction intersecting the first direction above the organic insulation layer;
- a second inorganic insulation layer above the organic insulation layer covering the second detection electrode;
- a first connection wiring electrically connecting the first detection electrode and one of the plurality of wirings; and
- a second connection wiring electrically connecting the second detection electrode and another one of the plurality of wirings.

2. The display device according to claim 1, wherein a terminal region includes a plurality of terminal electrodes arranged along an end part of the substrate, the plurality of wirings extend towards the terminal region and each of the first connection wiring and the second connection wiring is connected with the corresponding terminal electrode via the plurality of wirings.

3. The display device according to claim 2, wherein the first connection wiring is connected with one of the plurality of wirings via a first contact hole arranged in the interlayer insulation layer, and the second connection wiring is connected with another of the plurality of wirings via a second contact hole arranged in the interlayer insulation layer.

4. The display device according to claim 3, wherein an end part of the organic insulation layer is arranged to the inner side than an end part of the first inorganic insulation layer and the second inorganic insulation layer, and is arranged further to the inner side than the first contact hole and the second contact hole above the substrate.

5. The display device according to claim 3, wherein the first connection wiring and the second connection wiring are between the first inorganic insulation layer and the second inorganic insulation layer.

6. The display device according to claim 4, wherein the interlayer insulation layer includes at least one layer of an inorganic interlayer insulation layer and an organic interlayer insulation layer, and includes a stacked region stacked with the inorganic interlayer insulation layer and the organic interlayer insulation layer, and an opening region from which the organic interlayer insulation layer is removed and the inorganic interlayer insulation layer remains, and end part of the organic insulation layer overlapping with the opening region.

7. The display device according to claim 6, wherein the first contact hole and the second contact hole are arranged further to the outer side than the opening region.

8. The display device according to claim 7, wherein each of the first connection wiring and the second connection wiring respectively extends to the first contact hole and the second contact hole through the opening region.

9. The display device according to claim 1, wherein the organic insulation layer includes at least one type of an acrylic resin, a polyimide resin or an epoxy resin.

10. The display device according to claim 1, wherein the first inorganic insulation layer and the second inorganic insulation layer include at least one type or a plurality of types of a silicon nitride film, a silicon nitride oxide film or an aluminum oxide film.

11. A display device comprising:

a plurality of wirings above a substrate having an insulation surface;

an interlayer insulation layer covering the plurality of wirings;

a pixel region arranged with a plurality of pixels including a light emitting element above the substrate having the insulation surface;

a sealing layer over the interlayer insulation layer and covering the pixel region;

a first detection electrode extending in a first direction and a second detection electrode extending in a second direction intersecting the first direction above the pixel region;

a first connection wiring electrically connecting the first detection electrode and one of the plurality of wirings; and

a second connection wiring electrically connecting the second detection electrode and another wire included in the plurality of wirings,

wherein

the sealing layer includes an organic insulation layer, a first inorganic insulation layer arranged on a lower layer side of the organic insulation layer, and a second inorganic insulation layer arranged on an upper layer side of the organic insulation layer; and

one of the first detection electrode and the second detection electrode is arranged on an upper layer side of the organic insulation layer and the other is arranged on a lower layer side of the organic insulation layer, both being arranged sandwiching the organic insulation layer.

12. The display device according to claim 11, wherein a terminal region includes a plurality of terminal electrodes arranged along an end part of the substrate, the plurality of wirings extend towards the terminal region and the first connection wiring and each of the second connection wiring is connected with the corresponding terminal electrode via the plurality of wirings.

13. The display device according to claim 12, wherein the first connection wiring is connected with one of the plurality of wirings via a first contact hole arranged in the interlayer insulation layer, and the second connection wiring is connected with another of the plurality of wirings via a second contact hole arranged in the interlayer insulation layer.

14. The display device according to claim 11, wherein the interlayer insulation layer includes a plurality of inorganic interlayer insulation layers and at least one layer of an organic interlayer insulation layer, and includes a stacked region stacked with the plurality of inorganic interlayer insulation layers and the organic interlayer insulation layer, and an opening region from which the organic interlayer insulation layer is removed and the plurality of inorganic interlayer insulation layers remains, and end part of the organic insulation layer overlapping with the opening region.

15. The display device according to claim 14, wherein the sealing layer an end part of the organic insulation layer overlaps with the opening region, and an end part of the first inorganic insulation layer and the second inorganic insulation layer is arranged further to the outer side than the opening region.

16. The display device according to claim 13, wherein the first contact hole and second contact hole are arranged further to the outer side than the opening region of the interlayer insulation layer.

17. The display device according to claim 13, wherein the first connection wiring and the second connection wiring are between the first inorganic insulation layer and the second inorganic insulation layer.

18. The display device according to claim 11, wherein the organic insulation layer is a film of at least one type or plurality of types of an acrylic resin, a polyimide resin or an epoxy resin.

19. The display device according to claim 11, wherein the first inorganic insulation layer and the second inorganic insulation layer are at least one type or a plurality of types of a silicon nitride film, a silicon nitride oxide film or an aluminum oxide film.

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[标]申请(专利权)人(译)	株式会社日本显示器		
申请(专利权)人(译)	日本展示INC.		
当前申请(专利权)人(译)	日本展示INC.		
[标]发明人	HIRAGA KENTA AKIMOTO HAJIME		
发明人	HIRAGA, KENTA AKIMOTO, HAJIME		
IPC分类号	H01L27/32 H01L51/52 H01L27/12		
CPC分类号	H01L27/323 H01L51/524 H01L51/0002 H01L27/1203 H01L27/124 G06F3/0412 G06F3/044 G06F2203/04102 H01L51/5256 H01L27/3246 H01L27/3258 H01L27/3276 H01L51/5203 H01L51/5237		
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摘要(译)

根据本发明实施例的显示装置包括基板，绝缘表面上方的多个布线，覆盖多个布线的层间绝缘层，层间绝缘层上方的发光元件，第一无机绝缘层覆盖发光元件，在第一无机绝缘层上方沿第一方向延伸的第一检测电极，覆盖第一检测电极的第一无机绝缘层上方的有机绝缘层，沿与第一方向交叉的第二方向延伸的第二检测电极在有机绝缘层上方，覆盖第二检测电极的有机绝缘层上方的第二无机绝缘层，将第一检测电极与多个布线中的一个电连接的第一连接布线，以及电连接第二检测的第二连接布线选乘坐多个布线中的另一个。

